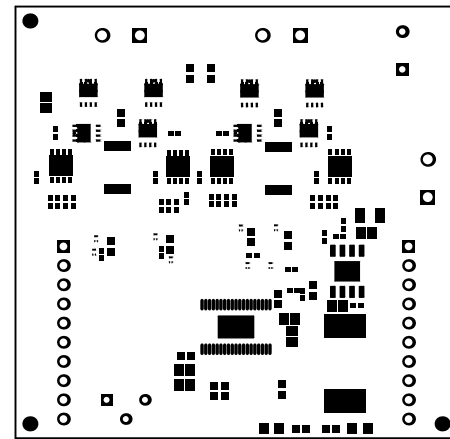
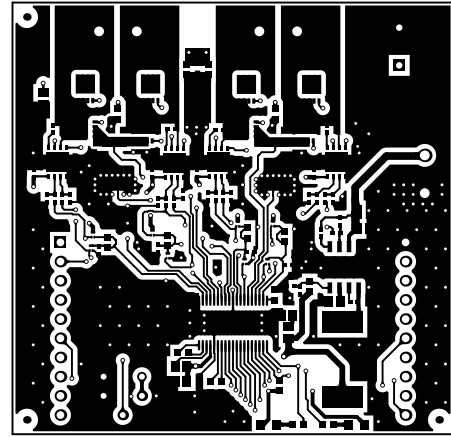


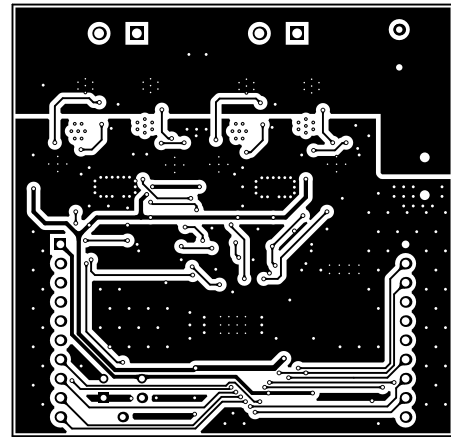
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01227	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 12/5/2016 10:54:14 AM	TEXAS INSTRUMENTS	



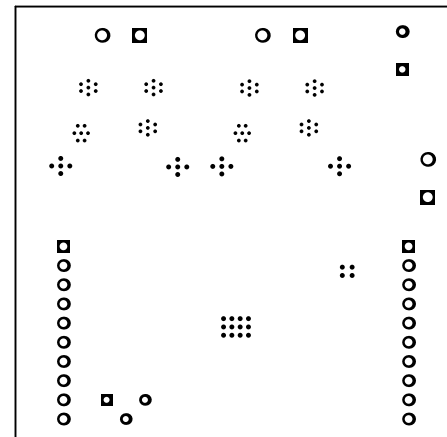
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01227	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 12/5/2016 10:54:19 AM	TEXAS INSTRUMENTS	



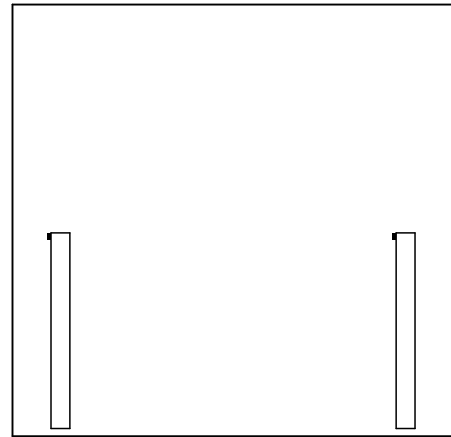
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01227	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 12/5/2016 10:54:24 AM	TEXAS INSTRUMENTS	



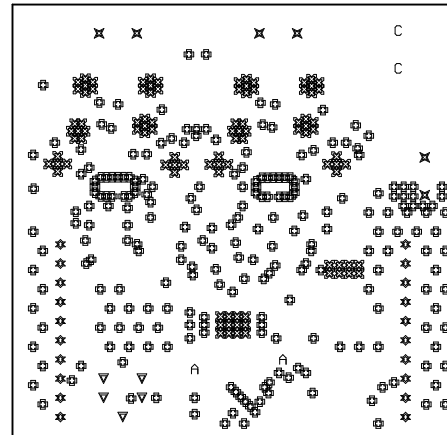
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01227	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 12/5/2016 10:54:28 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01227	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 12/5/2016 10:54:32 AM	TEXAS INSTRUMENTS	

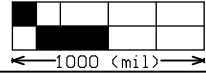
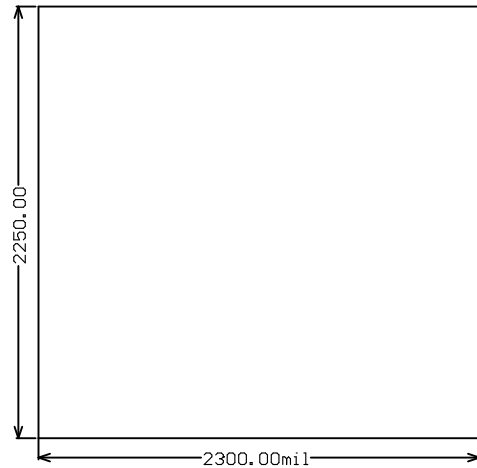


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01227	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 12/5/2016 10:54:37 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
⊗	96	7.87mil (0.200mm)	PTH	Round
⊙	241	15.00mil (0.381mm)	PTH	Round
A	2	18.00mil (0.457mm)	PTH	Round
▼	5	31.00mil (0.787mm)	PTH	Round
C	2	33.46mil (0.850mm)	PTH	Round
*	20	40.16mil (1.020mm)	PTH	Round
X	6	51.18mil (1.300mm)	PTH	Round
	372 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01227	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 12/5/2016 10:54:41 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01227	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 12/5/2016 10:54:46 AM	TEXAS INSTRUMENTS	

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